Customer Information Notification

201511016I

Issue Date: 28-Nov-2015
Effective Date: 28-Dec-2015

Here’s your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

Management Summary

The metal protrusions (connected to the source) at the drain side are relocated to the short side of the package.

Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[ ] Wafer Fab location
[X] Assembly Process
[ ] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[ ] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

Change position of metal protrusions in SOT1223AB3 package

Information Notification

The metal protrusions (connected to the source) at the drain side of the package are relocated to the short side of the package (see also attached document).
The metal protrusion do not have any functionality once NXP package assembly process is finished.

Why do we issue this Information Notification

In a continuous drive to increase the consistency of our products and its applications, the protrusions at the drain side have been put at the side of the devices, which enables the device to be pushed optimum to the drain side, narrowing down further production spread and improving overall performance of customers applications.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Hans Buis
Position	Process Improvement Manager
e-mail address	Hans.Buis@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

View Notification	Subscription	Support

Part Affected
BLP7G07S-140PY
BLP7G07S-140PY